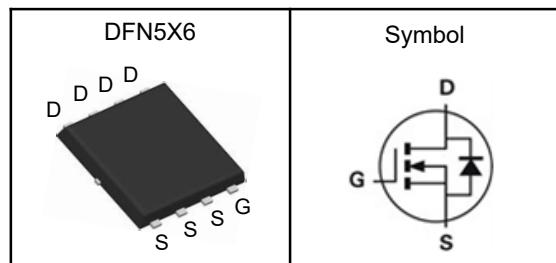


## N-Channel Enhancement Mode MOSFET

### Features

- Advanced SGT technology
- High Speed Power Switching
- Reliable and Rugged
- ROHS Compliant
- 100% Avalanche Tested

### Pin Description



### Applications

- Power Management in Desktop Computer
- DC/DC Converters

$V_{DSS}$	150	V
$R_{DS(ON)-Typ}$	9.5	$\text{m}\Omega$
$I_D$	75	A

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	150	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	300	A
$I_D$	Continuous Drain Current	75	A
$P_D$	Maximum Power Dissipation	125	W
$E_{AS}$	Avalanche Energy, Single pulse	205	mJ

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	54	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ\text{C}$ .

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz.

**N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics (T<sub>J</sub>=25°C, Unless Otherwise Noted)**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	150	---	---	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V	---	---	1	uA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2.0	---	4.0	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	9.5	11.5	mΩ
<b>Dynamic Characteristics<sup>⑤</sup></b>						
g <sub>FS</sub>	Gate Resistance	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	---	69	---	S
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =75V, V <sub>GS</sub> =0V, Freq.=1MHz	---	3350	---	pF
C <sub>oss</sub>	Output Capacitance		---	268	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	9.4	---	
T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =75V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A, R <sub>G</sub> =3Ω	---	16	---	nS
T <sub>r</sub>	Turn-on Rise Time		---	12	---	
T <sub>d(off)</sub>	Turn-off Delay Time		---	30	---	
T <sub>f</sub>	Turn-off Fall Time		---	18	---	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =75V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	46	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	15	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	8.5	---	
<b>Source-Drain Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, V <sub>GS</sub> =0V, dI <sub>F</sub> /dt=100A/us	---	76	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	182	---	nC

Note ④: Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

## N-Channel Enhancement Mode MOSFET

### Typical Characteristics

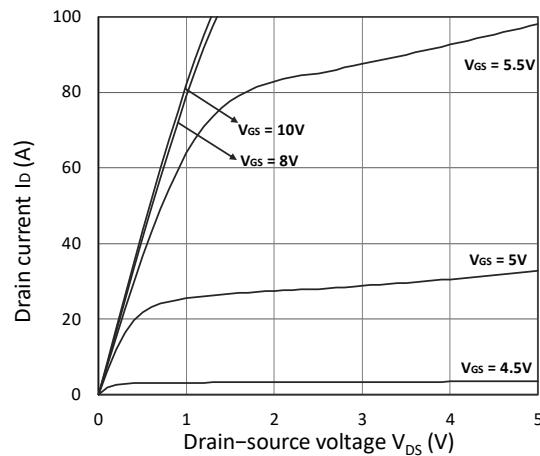


Figure 1. Output Characteristics

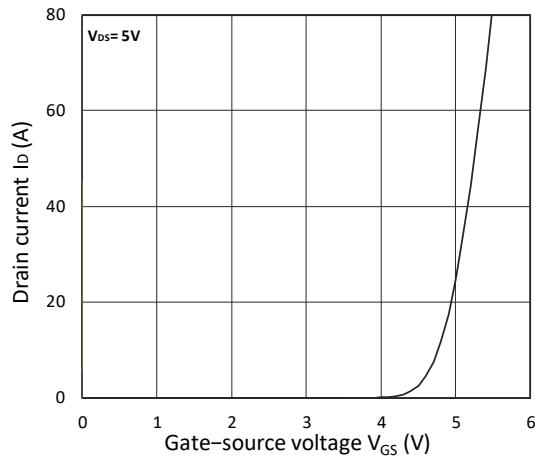


Figure 2. Transfer Characteristics

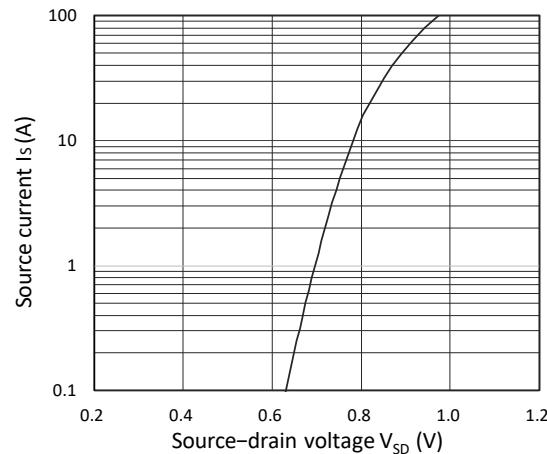


Figure 3. Forward Characteristics of Reverse

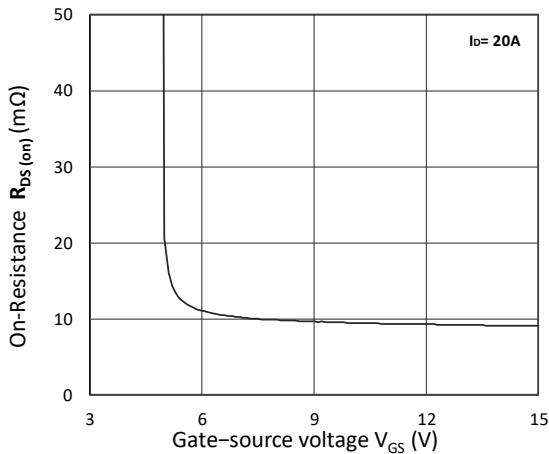


Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$

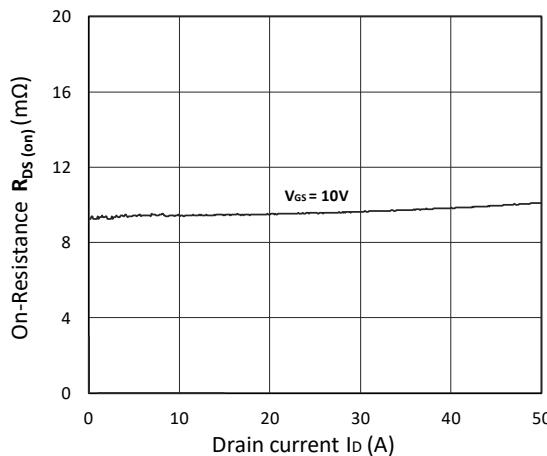


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

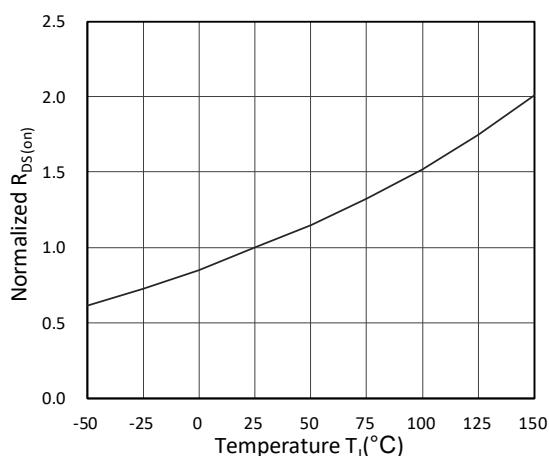


Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

## N-Channel Enhancement Mode MOSFET

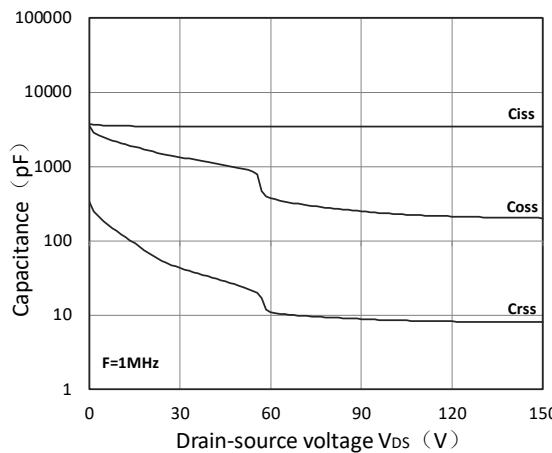


Figure 7. Capacitance Characteristics

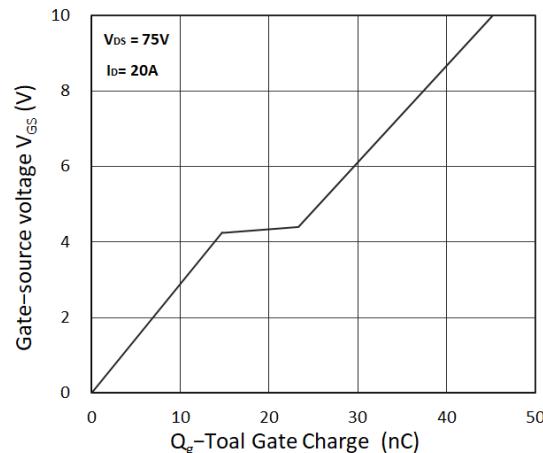


Figure 8. Gate Charge Characteristics

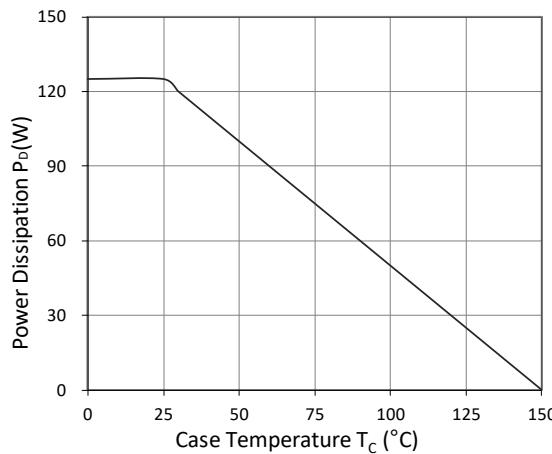


Figure 9. Power Dissipation

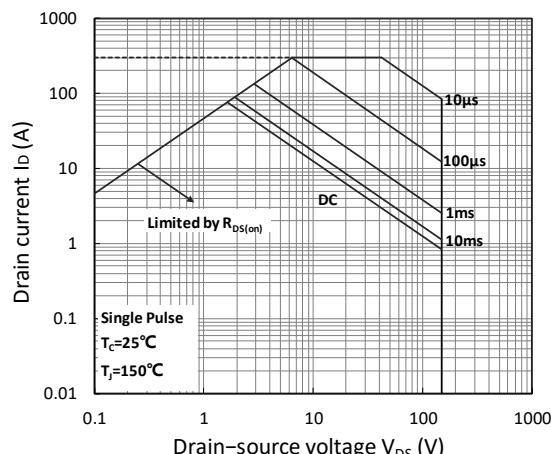


Figure 10. Safe Operating Area

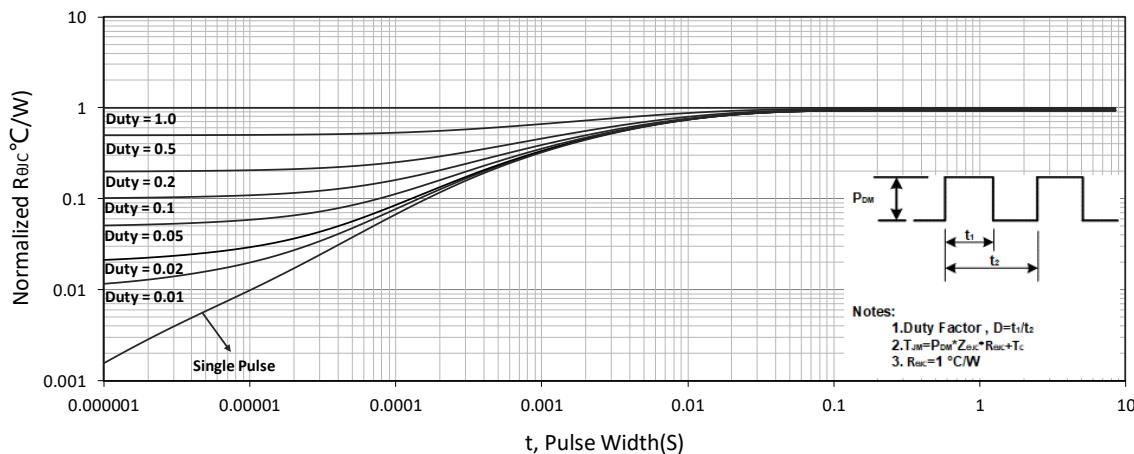
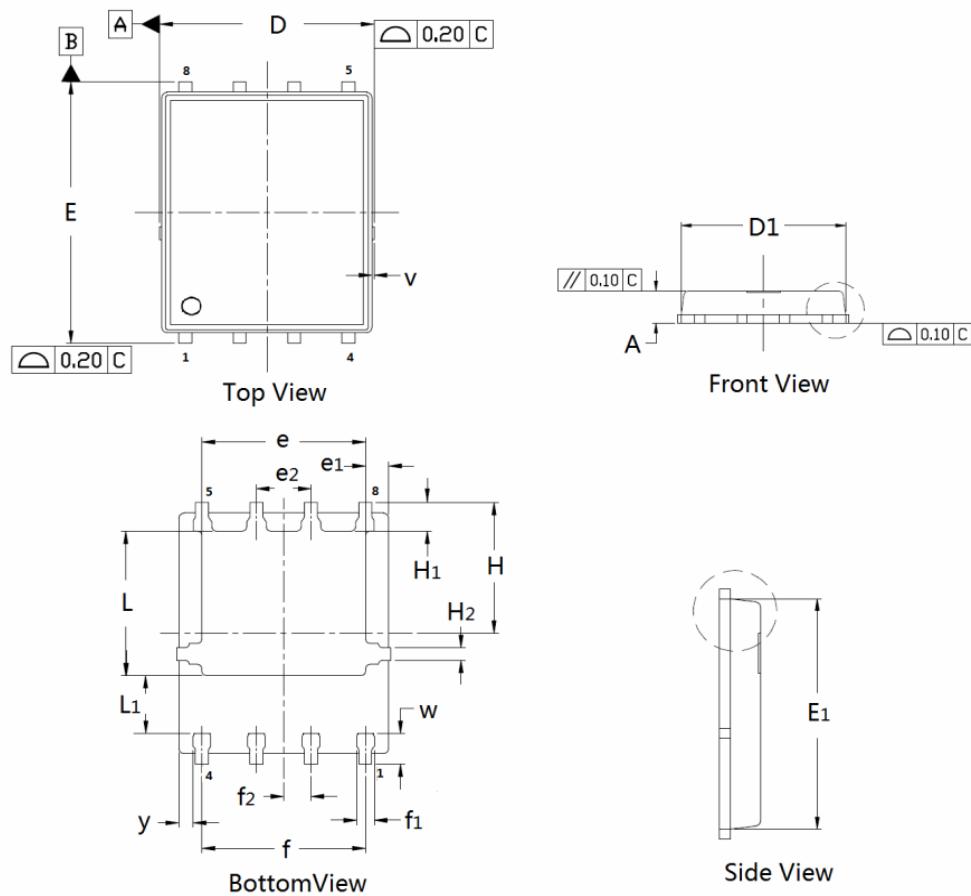


Figure 11. Normalized Maximum Transient Thermal Impedance

**N-Channel Enhancement Mode MOSFET**
**DFN5×6 Package Outline Data**

**DIMENSIONS (unit : mm)**

Symbol		Typ	Max	Symbol	Min	Typ	Max
<b>A</b>	0.90	1.02	1.10	<b>D</b>	4.90	4.98	5.10
<b>D<sub>1</sub></b>	4.80	4.89	5.10	<b>E</b>	5.90	6.11	6.25
<b>E<sub>1</sub></b>	5.65	5.74	5.95	<b>e</b>	3.72	3.80	3.92
<b>e<sub>1</sub></b>	--	0.5	--	<b>e<sub>2</sub></b>	--	1.	--
<b>f</b>	--	3.8	--	<b>f<sub>1</sub></b>	0.31	0.37	0.51
<b>f<sub>2</sub></b>	--	0.6	--	<b>H</b>	--	3.	--
<b>H<sub>1</sub></b>	0.59	0.63	0.79	<b>H<sub>2</sub></b>	0.26	0.28	0.32
<b>L</b>	3.35	3.45	3.65	<b>L<sub>1</sub></b>	--	1.	--
<b>V</b>	--	0.1	--	<b>w</b>	0.64	0.68	0.84
<b>y</b>	--	0.3	--		--		--



FSH15N095GT

N-Channel Enhancement Mode MOSFET

## 印字说明

### 印字说明

FSH15N095GT

BBCC

第一行标记为物料型号代码

第二行BB为表示年份，例如22即表示2022年，CC表示周期，例如01即表示第一周; 2201即表示2022年第一周生产。